

**MICROCHIP****PIC18F2423/2523/4423/4523****PIC18F2423/2523/4423/4523 Rev. B4 Silicon Errata**

The PIC18F2423/2523/4423/4523 Rev. B4 parts you have received conform functionally to the Device Data Sheet (DS39755B), except for the anomalies described below. Any Data Sheet Clarification issues related to the PIC18F2423/2523/4423/4523 will be reported in a separate Data Sheet errata. Please check the Microchip web site for any existing issues.

The following silicon errata apply only to PIC18F2423/2523/4423/4523 devices with these Device/Revision IDs:

Part Number	Device ID	Revision ID
PIC18F2423	0001 0001 0100	0111
PIC18F2523	0001 0001 0000	0111
PIC18F4423	0001 0000 1100	0111
PIC18F4523	0001 0000 1000	0111

The Device IDs (DEVID1 and DEVID2) are located at addresses 3FFFFEh:3FFFFFh in the device's configuration space. They are shown in binary in the format "DEVID2 DEVID1".

All of the issues listed here will be addressed in future revisions of the PIC18F2423/2523/4423/4523 silicon.

1. Module: MSSP

In SPI Slave mode with slave select enabled (SSPM<3:0> = 0100), the minimum time between the falling edge of the SS pin and first SCK edge is greater than specified in parameter 70 in Table 26-16 and Table 26-17 of the above referenced data sheet.

The updated specification is shown in bold in Table 1.

Work around

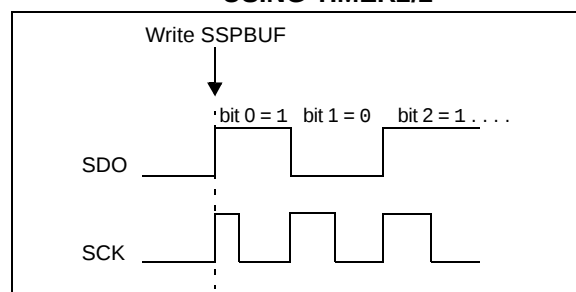
None.

Date Codes that pertain to this issue:

All engineering and production devices.

2. Module: MSSP (SPI Mode)

When the SPI is using Timer2/2 as the clock source, a shorter than expected SCK pulse may occur on the first bit of the transmitted/received data (Figure 1).

FIGURE 1: SCK PULSE VARIATION USING TIMER2/2**Work around**

To avoid producing the short pulse, turn off Timer2 and clear the TMR2 register, load the SSPBUF with the data to transmit and then turn Timer2 back on. Refer to Example 1 for sample code.

EXAMPLE 1: AVOIDING THE INITIAL SHORT SCK PULSE

```

LOOP BTFSS SSPSTAT, BF      ;Data received?
                                ;(Xmit complete?)
    BRA    LOOP              ;No
    MOVF   SSPBUF, W          ;W = SSPBUF
    MOVWF  RXDATA             ;Save in user RAM
    MOVF   TXDATA, W          ;W = TXDATA
    BCF    T2CON, TMR2ON      ;Timer2 off
    CLRF   TMR2               ;Clear Timer2
    MOVWF  SSPBUF             ;Xmit New data
    BSF    T2CON, TMR2ON      ;Timer2 on

```

Date Codes that pertain to this issue:

All engineering and production devices.

TABLE 1: EXAMPLE SPI MODE REQUIREMENTS (SLAVE MODE TIMING)

Param No.	Symbol	Characteristic	Min	Max	Units	Conditions
70	TssL2scl, TssL2sch	SS ↓ to SCK ↓ or SCK ↑ Input	3 Tcy	—	ns	

PIC18F2423/2523/4423/4523

3. Module: Enhanced Universal Synchronous Receiver Transmitter (EUSART)

One bit has been added to the BAUDCON register and one bit has been renamed. The added bit is RXDTP and is in the location, BAUDCON<5>. The renamed bit is the TXCKP bit (BAUDCON<4>), which had been named SCKP.

The TXCKP (BAUDCON<4>) and RXDTP (BAUDCON<5>) bits enable the TX and RX signals to be inverted (polarity reversed).

Register 18-3, on page 208, will be changed as shown.

Work around

None required.

Date Codes that pertain to this issue:

All engineering and production devices.

REGISTER 18-3: BAUDCON: BAUD RATE CONTROL REGISTER

R/W-0	R-1	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 7 **ABDOVF**: Auto-Baud Acquisition Rollover Status bit
1 = A BRG rollover has occurred during Auto-Baud Rate Detect mode (must be cleared in software)
0 = No BRG rollover has occurred
- bit 6 **RCIDL**: Receive Operation Idle Status bit
1 = Receive operation is Idle
0 = Receive operation is Active
- bit 5 **RXDTP**: Receive Data Polarity Select bit
Asynchronous mode:
1 = Receive data (RX) is inverted. Idle state is a low level.
0 = No inversion of receive data (RX). Idle state is a high level.
Synchronous mode:
1 = Data (DT) is inverted. Idle state is a low level.
0 = No inversion of data (DT). Idle state is a high level.
- bit 4 **TXCKP**: Transmit/Clock Polarity Select bit
Asynchronous mode:
1 = Transmit data (TX) is inverted. Idle state is a low level.
0 = No inversion of transmit data (TX). Idle state is a high level.
Synchronous mode:
1 = Idle state for clock (CK) is a high level
0 = Idle state for clock (CK) is a low level
- bit 3 **BRG16**: 16-bit Baud Rate Register Enable bit
1 = 16-bit Baud Rate Generator – SPBRGH and SPBRG
0 = 8-bit Baud Rate Generator – SPBRG only (Compatible mode); SPBRGH value ignored
- bit 2 **Unimplemented**: Read as '0'

REGISTER 18-3: BAUDCON: BAUD RATE CONTROL REGISTER (CONTINUED)

- bit 1 **WUE:** Wake-up Enable bit
Asynchronous mode:
1 = EUSART will continue to sample the RX pin with the interrupt generated on the falling edge; bit cleared in hardware on following rising edge
0 = RX pin is not monitored or rising edge detected
Synchronous mode:
Unused in this mode.
- bit 0 **ABDEN:** Auto-Baud Detect Enable bit
Asynchronous mode:
1 = Enable baud rate measurement on the next character. Requires reception of a Sync field (55h); cleared in hardware upon completion.
0 = Baud rate measurement disabled or completed
Synchronous mode:
Unused in this mode.

4. Module: 12-Bit Analog-to-Digital Converter

When the AD clock source is selected as 2 Tosc or RC (when $ADCS<2:0> = 000$ or $x11$), in extremely rare cases, the EIL (Integral Linearity Error) and EDL (Differential Linearity Error) may exceed the data sheet specification at codes 511 and 512 only.

Work around

Select the AD clock source as 4 Tosc, 8 Tosc, 16 Tosc, 32 Tosc or 64 Tosc and avoid selecting 2 Tosc or RC.

Date Codes that pertain to this issue:

All engineering and production devices.

5. Module: MSSP

With MSSP in SPI Master mode, $F_{osc}/64$ or Timer2/2 clock rate, and $CKE = 0$, a write collision may occur if SSPBUF is loaded immediately after the transfer is complete. A delay may be required after the MSSP Interrupt Flag bit, SSPIF, is set or the Buffer Full bit, BF, is set and before writing SSPBUF. If the delay is insufficiently short, a write collision may occur as indicated by the WCOL bit being set.

Work around

Add a software delay of one SCK period after detecting the completed transfer and prior to updating the SSPBUF contents. Verify the WCOL bit is clear after writing SSPBUF. If the WCOL is set, clear the bit in software and rewrite the SSPBUF register.

Date Codes that pertain to this issue:

All engineering and production devices.

6. Module: Enhanced Capture/Compare/ PWM (ECCP)

With the ECCP configured for Half-Bridge PWM mode ($CCP1M<3:0> = 1110$), the output may be corrupted for particular duty cycle selections. Affected duty cycle values are 0 through 3, and every subsequent increment of 4 (i.e., 7, 11, 15, 19, etc.).

Work around

None.

Date Codes that pertain to this issue:

All engineering and production devices.

7. Module: Resets (BOR)

An unexpected Reset may occur if the Brown-out Reset module (BOR) is disabled, and then re-enabled, when the High/Low-Voltage Detection module (HLVD) is not enabled (HLVDCON<4> = 0).

This issue affects BOR modes: BOREN<1:0> = 10 and BOREN<1:0> = 01. In both of these modes, if the BOR module is re-enabled while the device is active, unexpected Resets may be generated.

Work around

If BOR is required, and power consumption is not an issue, use BOREN<1:0> = 11. For BOREN<1:0> = 10 mode, either switch to BOREN<1:0> = 11 mode or enable the HLVD (HLVDCON<4> = 1) prior to entering Sleep.

If power consumption is an issue and low power is desired, Microchip does not recommend using BOREN<1:0> = 10 mode. Instead, use BOREN<1:0> = 01 and follow the steps below when entering and exiting Sleep.

1. Disable BOR by clearing SBOREN (RCON<6> = 0).
2. Enter Sleep mode (if desired).
3. After exiting Sleep mode, enable the HLVD (HLVDCON<4> = 1).
4. Wait for the internal reference voltage (T_{IRVST}) to stabilize (typically 20 μ s).
5. Re-enable BOR by setting SBOREN (RCON<6> = 1).
6. Disable the HLVD by clearing HLV DEN (HLVDCON<4> = 0).

Date Codes that pertain to this issue:

All engineering and production devices.

REVISION HISTORY

Rev A Document (10/2008)

Initial release of this document. Includes silicon issues 1 (MSSP), 2 (MSSP – SPI Mode), 3 (Enhanced Universal Synchronous Receiver Transmitter – EUSART), 4 (10-Bit Analog-to-Digital Converter), 5 (MSSP), 6 (Enhanced Capture/Compare/PWM – ECCP) and 7 (Resets – BOR).

PIC18F2423/2523/4423/4523

NOTES:

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